Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	39786	copper near3 foil	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 12:45
L3	7539	(electrolytic electrochemical) adj polish\$3 electropolish\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 19:21
L4	90	L2 and L3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 15:47
L9	30	c25f003/18.ipc.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 15:49
L10	143	c25f003/22.ipc.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 15:49
L11	171	9 10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 15:49
L12	5	copper and foil and 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 15:51
L13	6	cu adj foil and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:02

L14	1628416	copper cu	US-PGPUB;	OR	ON	2005/11/20 16:02
LIT	1020410	copper cu	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OK .	OIV	2005/11/30 16:03
L15	10743	cathod\$2 adj plate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:04
L16	25613	pickling	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:03
L17	3	3 and 14 and 15 and 16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:03
L18	100	cathod\$2 adj plate and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:11
L19	108	acid\$2 with pickling with copper.ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:11
L20	6	acid\$2 with pickling with copper adj foil.ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:20
L21	110456	copper near3 (film strip foil plate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:22

L22	27	2 with 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:21
L23	110	21 with 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:21
L24	126450	(cu copper) near3 (film strip foil plate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:22
L25	118	24 with 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:23
L26	7	24 with 3 and pickl\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:24
L27	1	"62200796"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:30
L28	138	pickling.ti. and copper.ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 17:29
L29	17	copper adj foil with rolling with electrodeposition	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 17:30

L30	1	copper adi foil with rolling with	US-PGPUB;	OR	ON	2005/11/20 17:20
230	1	copper adj foil with rolling with electrodeposition.ab.	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OK	ON	2005/11/30 17:30
L31	2	copper adj foil with rolling with (electrodeposit\$3 electroplat\$3 (electrolytic electrochemical) adj (deposit\$3 plat\$3)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 17:33
L32	2	copper adj foil same rolling with (electrodeposit\$3 electroplat\$3 (electrolytic electrochemical) adj (deposit\$3 plat\$3)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 17:33
L33	51	copper adj foil same rolling with (electrodeposit\$3 electroplat\$3 (electrolytic electrochemical) adj (deposit\$3 plat\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 18:26
L34	33	copper adj foil with (clean\$3 wash\$3) with (water aqeous).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 18:34
L35	199730	copper adj foil with (polish\$3 electropolish\$3) (clean\$3 wash\$3) with (water aqeous).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 18:28
L36	3	copper adj foil with (polish\$3 electropolish\$3) with (clean\$3 wash\$3) with (water aqeous).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 18:29
L37	48	copper adj foil with (polish\$3 electropolish\$3) with (clean\$3 wash\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 18:30

L38	27	copper adj foil with (polish\$3 electropolish\$3) with (clean\$3 wash\$3) with (water aqeous)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 18:33
L39	13	water near3 bath with wash\$3 with copper adj foil	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 18:33
L40		copper adj foil with (rough\$) with (clean\$3 wash\$3) with (water aqeous).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 18:35
L41	33	copper adj foil with (clean\$3 wash\$3) with (water aqeous).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 19:08
L42	0	("362188785").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 19:08
L43	0	"362188785"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 19:08
L44	0	"bright pickling solution for copper and copper alloy"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 19:08
L45	. 0	"bright pickling solution for copper "	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 19:09

L46	0	"bright pickling solution for copper"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 19:09
L47	2	"bright pickling solution copper"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 19:11
L48	1	("51025766").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 19:14
L49	0	("(chromicadjacidureamercaptan)withcorrosionwithcopperadjfoil").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 19:15
L50	6	(chromic adj acid urea mercaptan) with corrosion with copper adj foil	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 19:19
L51	136	(chromic adj acid urea mercaptan) with corrosion with copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 19:17
L52	1	(chromic adj acid urea mercaptan) with corrosion with copper and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 19:18
L53	19	(chromic adj acid urea mercaptan) with corrosion with copper and (electrolytic electrochemical electropolish\$3 electroetch\$3 electroremov\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 19:18

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L54	75	(chromic adj acid urea mercaptan) with copper adj foil	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 19:20
L55	812	(chromic adj acid urea mercaptan) with copper.ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 19:20
L56	2	(chromic adj acid urea mercaptan) with copper.ab. and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 19:21
L57	7850	(electrolytic\$5 electrochemical\$5) adj polish\$3 electropolish\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 19:21
L58	2	(chromic adj acid urea mercaptan) with copper.ab. and 57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 19:24
L59	20	copper adj sulfate with corrosion adj inhibitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:13
L60	17	(temperature degree) with effect with 57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:15
L61	0	(temperature degree) with rate with 57.ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:16

L62	60	(temperature degree) with rate and 57.ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:16
L63	874	(temperature degree) with rate and 57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:16
L65	32	(temperature degree) with rate.ab. and 57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:19
L66	2	(temperature degree) with fast\$3. ab. and 57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:19
L67	599	(temperature degree) with effect and 57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:19
L68	12	(temperature degree) with effect. ab. and 57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:26
L69	1	ph with effect with 57.ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:27
L70	0	ph with rate with 57.ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:27

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L71	6	ph.ab. with rate and 57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:27
L72	48	ph with increase and 57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:30
L73	0	11 and ph near3 effect	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:30
L74	0	11 and ph with effect	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:30
L75	14	11 and ph	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:31
L76	2	205/640-686	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:32
L77		(205/640/686).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 20:32
L78	0	77 and ph near5 effect	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:32

L79	3457	(205/640-686).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 20:32
L80	15	79 and ph near5 effect	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:34
L81	0	79 and acidity near5 effect	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:34
L82	0	79 and acidity near5 rate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:34
L83	10	79 and ph near5 rate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:43
L84	0	corrosion adj inhibitor near5 effect and 79	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:44
L85	6	corrosion adj inhibitor near5 rate and 79	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 20:57
L86	2	("5449411").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 21:04

L87	2	("5792333").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 21:05
L88	2	("5834140").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 21:05
S1	. 0	("10722469").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/03 14:45
S2	2	("20040108216").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/03 14:46
S3	3450	(205/640-686).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/03 14:46
S4	39590	copper near3 foil	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:46
S5	47	S3 and S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:54
S6	7490	(electrolytic electrochemical) adj polish\$3 electropolish\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 12:45

S7	13	CE and CE	LIC DCDUB	OB	ON	2005/11/02 15:12
5/	13	S5 and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 15:13
S8	14	cathode adj plate with electropolish\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 15:15
S9	10479	cathode adj plate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 15:15
S10	370	cathode adj plate with shape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 15:53
S11	52385	("205").CLAS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/03 15:15
S12	43	S10 and S11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 15:15
S13	7	cathode adj plate and S6 and foil	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 15:57
S14	29	cathode near6 plate and S6 and foil	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 15:57

S15	22	cathode near6 plate and S6 and foil not S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 16:00
S16	28	(cathode adj plate plate adj cathode) and S6 with copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 16:01